CLEAN VERSION OF CLAIMS

1. An electronic sub assembly comprising a circuitized laminated substrate having top and bottom surfaces, and at least one beveled edge surface between said top and bottom surfaces, at least one active or passive device mounted on said at least one edge surface, at least one active or passive device mounted on at least one of the top and bottom surfaces, a conductive lead embedded in the substrate electrically connected to an active or passive device mounted on said at least one edge surface, the conductive lead also electrically connected to at least one device on the top or bottom surface.

2. The sub assembly according to claim 1 wherein each of the active or passive devices is selected from the group including chips, diodes, resistors, capacitors and printed wiring boards.

3. The sub assembly according to claim 1 further including an electrically conductive via extending into the substrate from each device on the top or bottom surface into contact with a conductive lead connected to an edge mounted device.

4. The sub assembly according to claim 1 wherein the laminated substrate is selected from the group comprising a single or multiple laminates

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of a fiberglass reinforced prepreg and a conductive layer, and a single or multiple laminates of a ceramic module and a conductive layer.

8. A printed circuit board having two spaced apart, generally parallel surfaces comprising a top surface and a bottom surface, a beveled edge surface between said top and bottom surfaces, a plurality of conductive leads embedded in the circuit board parallel to the top and bottom surfaces and terminating in one or more connection points along the beveled edge surface, an active or passive device mounted on said edge surface and electrically joined through at least one of said connection points to at least one of the conductive leads, and at least one other active or passive device mounted on the top or bottom surface electrically joined through one of said conductive leads to the edge mounted device.

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9. The printed circuit board according to claim 8 further including a via on the top or bottom surface, and coupled to a top or bottom mounted device, said via extending into the substrate into contact with a conductive lead connected to said edge mounted device.

10. The printed circuit board according to claim 8 wherein each active or passive device is selected from the group including chips, diodes, resistors, capacitors and printed wiring boards.

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27. The electronic sub assembly according to claim 1 wherein the edge surface is beveled at an angle of between 30° and 60° with respect to the top or bottom surface.

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28. The printed circuit board according to claim 8 wherein the edge surface is beveled at an angle of between 30° and 60° with respect to the top or bottom surface.

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